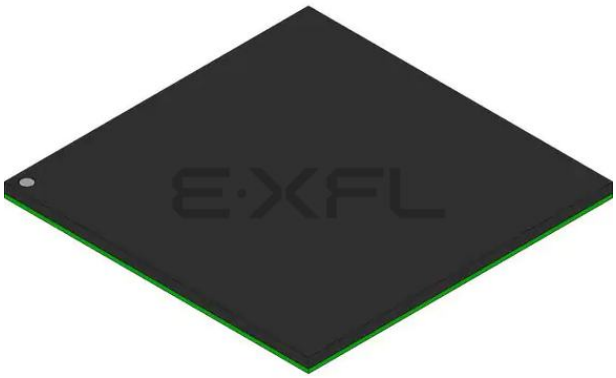

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	ARM920T
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	150MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	LCD
Ethernet	-
SATA	-
USB	USB 1.x (1)
Voltage - I/O	1.8V, 3.0V
Operating Temperature	-40°C ~ 85°C (TA)
Security Features	-
Package / Case	256-LFBGA
Supplier Device Package	256-PBGA (14x14)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9328mxlcvm15

- A *pin* is an external physical connection. The same pin can be used to connect a number of signals.
- *Asserted* means that a discrete signal is in active logic state.
  - — *Active low* signals change from logic level one to logic level zero.
  - — *Active high* signals change from logic level zero to logic level one.
- *Negated* means that an asserted discrete signal changes logic state.
  - — *Active low* signals change from logic level zero to logic level one.
  - — *Active high* signals change from logic level one to logic level zero.
- LSB means *least significant bit* or *bits*, and MSB means *most significant bit* or *bits*. References to low and high bytes or words are spelled out.
- Numbers preceded by a percent sign (%) are binary. Numbers preceded by a dollar sign ($) or *0x* are hexadecimal.

2 Signals and Connections

Table 2 identifies and describes the i.MXL processor signals that are assigned to package pins. The signals are grouped by the internal module that they are connected to.

Table 2. i.MXL Signal Descriptions

Signal Name	Function/Notes
External Bus/Chip-Select (EIM)	
A[24:0]	Address bus signals
D[31:0]	Data bus signals
$\overline{EB0}$	MSB Byte Strobe—Active low external enable byte signal that controls D [31:24].
$\overline{EB1}$	Byte Strobe—Active low external enable byte signal that controls D [23:16].
$\overline{EB2}$	Byte Strobe—Active low external enable byte signal that controls D [15:8].
$\overline{EB3}$	LSB Byte Strobe—Active low external enable byte signal that controls D [7:0].
$\overline{OE}$	Memory Output Enable—Active low output enables external data bus.
$\overline{CS}$ [5:0]	Chip-Select—The chip-select signals $\overline{CS}$ [3:2] are multiplexed with $\overline{CSD}$ [1:0] and are selected by the Function Multiplexing Control Register (FMCR). By default $\overline{CSD}$ [1:0] is selected.
$\overline{ECB}$	Active low input signal sent by a flash device to the EIM whenever the flash device must terminate an on-going burst sequence and initiate a new (long first access) burst sequence.
$\overline{LBA}$	Active low signal sent by a flash device causing the external burst device to latch the starting burst address.
BCLK (burst clock)	Clock signal sent to external synchronous memories (such as burst flash) during burst mode.
$\overline{RW}$	$\overline{RW}$ signal—Indicates whether external access is a read (high) or write (low) cycle. Used as a $\overline{WE}$ input signal by external DRAM.
$\overline{DTACK}$	$\overline{DTACK}$ signal—The external input data acknowledge signal. When using the external DTACK signal as a data acknowledge signal, the bus time-out monitor generates a bus error when a bus cycle is not terminated by the external DTACK signal after 1022 clock counts have elapsed.

Table 3. MC9328MXLMC9328MXS Signal Multiplexing Scheme (Continued)

I/O Supply Voltage	225 BGA Ball	256 BGA Ball	Primary			Alternate		GPIO		AIN	BIN	AOUT	Default
			Signal	Dir	Pull-Up	Signal	Dir	Mux	Pull-Up				
NVDD2	H13	N13	CSI_PIXCLK	I				PA14	69K				PA14
NVDD2	G14	M13	CSI_HSYNC	I				PA13	69K				PA13
NVDD2	H12	M14	CSI_VSYNC	I				PA12	69K				PA12
NVDD2	G13	N14	CSI_D7	I				PA11	69K				PA11
NVDD2	J10	M15	CSI_D6	I				PA10	69K				PA10
NVDD2	G15	M16	CSI_D5	I				PA9	69K				PA9
NVDD2	F15	M12	CSI_D4	I				PA8	69K				PA8
NVDD2	G12	L16	CSI_D3	I				PA7	69K				PA7
NVDD2	F14	L15	CSI_D2	I				PA6	69K				PA6
NVDD2	H11	L14	CSI_D1	I				PA5	69K				PA5
NVDD2	E14	L13	CSI_D0	I				PA4	69K				PA4
NVDD2	E15	L12	CSI_MCLK	O				PA3	69K				PA3
NVDD2	G11	L11	PWMO	O				PA2	69K				PA2
NVDD2	E13	L10	TIN	I				PA1	69K			SPI2_RXD_0	PA1
NVDD2	D14	K15	TMR2OUT	O				PD31	69K		SPI2_TXD		PD31
NVDD2	F13	K16	LD15	O				PD30	69K				PD30
NVDD2	F12	K14	LD14	O				PD29	69K				PD29
NVDD2	D15	K13	LD13	O				PD28	69K				PD28
NVDD2	C14	K12	LD12	O				PD27	69K				PD27
NVDD2	D13	J14	LD11	O				PD26	69K				PD26
NVDD2	E12	K11	LD10	O				PD25	69K				PD25
NVDD2	C13	H15	LD9	O				PD24	69K				PD24
NVDD2	C12	J13	LD8	O				PD23	69K				PD23
NVDD2	B15	J12	LD7	O				PD22	69K				PD22
NVDD2	B14	J11	LD6	O				PD21	69K				PD21
NVDD2	A15	H14	LD5	O				PD20	69K				PD20
NVDD2	A14	H13	LD4	O				PD19	69K				PD19
NVDD2	B13	H16	LD3	O				PD18	69K				PD18
NVDD2	A13	H12	LD2	O				PD17	69K				PD17
NVDD2	D12	G16	LD1	O				PD16	69K				PD16
NVDD2	B12	H11	LD0	O				PD15	69K				PD15
NVDD2	C11	G15	FLM/VSYNC	O				PD14	69K				PD14

Table 3. MC9328MXLMC9328MXS Signal Multiplexing Scheme (Continued)

I/O Supply Voltage	225 BGA Ball	256 BGA Ball	Primary			Alternate		GPIO		AIN	BIN	AOUT	Default
			Signal	Dir	Pull-Up	Signal	Dir	Mux	Pull-Up				
NVDD4	D8	F7	UART2_TXD	O				PB30	69K				PB30
NVDD4	E7	E7	$\overline{\text{UART2\_RTS}}$	I				PB29	69K				PB29
NVDD4	F7	C6	$\overline{\text{UART2\_CTS}}$	O				PB28	69K				PB28
NVDD4	B6	D7	USBD_VMO	O				PB27	69K				PB27
NVDD4	C6	D6	USBD_VPO	O				PB26	69K				PB26
NVDD4	A6	E6	USBD_VM	I				PB25	69K				PB25
NVDD4	D6	B6	USBD_VP	I				PB24	69K				PB24
NVDD4	A5	D5	USBD_SUSPND	O				PB23	69K				PB23
NVDD4	B5	C5	USBD_RCV	I/O				PB22	69K				PB22
NVDD4	A4	B5	$\overline{\text{USBD\_ROE}}$	O				PB21	69K				PB21
NVDD4	B4	A5	USBD_AFE	O				PB20	69K				PB20
NVDD4	A3	G7	PB19	I/O					69K				PB19
NVDD4	C4	F6	PB18	I/O					69K				PB18
NVDD4	D4	G6	PB17	O					69K				PB17
NVDD4	B3	B4	PB16	I					69K				PB16
NVDD4	A2	C4	PB15	I					69K				PB15
NVDD4	C3	D4	PB14	I					69K				PB14
NVDD4	A1	B3	SD_CMD	I/O		MS_BS		PB13	69K				PB13
NVDD4	B2	A3	SD_CLK	O		MS_SCLKO		PB12	69K				PB12
NVDD4	B1	A2	SD_DAT3	I/O		MS_SDIO		PB11	69K (pull down)				PB11
NVDD4	C5	E5	SD_DAT2	I/O		MS_SCLKI		PB10	69K				PB10
NVDD4	D3	B2	SD_DAT1	I/O		MS_PI1		PB9	69K				PB9
NVDD4	C2	C3	SD_DAT0	I/O		MS_PI0		PB8	69K				PB8
NVDD1	D5	K8	NVDD1	Static									
	G6	A1	NVSS	Static									
NVDD1	E5	H5	NVDD1	Static									
	H6	T1	NVSS	Static									
QVDD1	J8	H9	QVDD1	Static									
	E6	H8	QVSS	Static									

Table 9. Trace Port Timing Diagram Parameter Table (Continued)

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
4a	Output hold time	2.28	–	2	–	ns
4b	Output setup time	3.42	–	3	–	ns

4.2 DPLL Timing Specifications

Parameters of the DPLL are given in Table 10. In this table, T_{ref} is a reference clock period after the pre-divider and T_{dck} is the output double clock period.

Table 10. DPLL Specifications

Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
DPLL input clock freq range	Vcc = 1.8V	5	–	100	MHz
Pre-divider output clock freq range	Vcc = 1.8V	5	–	30	MHz
DPLL output clock freq range	Vcc = 1.8V	80	–	220	MHz
Pre-divider factor (PD)	–	1	–	16	–
Total multiplication factor (MF)	Includes both integer and fractional parts	5	–	15	–
MF integer part	–	5	–	15	–
MF numerator	Should be less than the denominator	0	–	1022	–
MF denominator	–	1	–	1023	–
Pre-multiplier lock-in time	–	–	–	312.5	µsec
Freq lock-in time after full reset	FOL mode for non-integer MF (does not include pre-multi lock-in time)	250	280 (56 µs)	300	T_{ref}
Freq lock-in time after partial reset	FOL mode for non-integer MF (does not include pre-multi lock-in time)	220	250 (50 µs)	270	T_{ref}
Phase lock-in time after full reset	FPL mode and integer MF (does not include pre-multi lock-in time)	300	350 (70 µs)	400	T_{ref}
Phase lock-in time after partial reset	FPL mode and integer MF (does not include pre-multi lock-in time)	270	320 (64 µs)	370	T_{ref}
Freq jitter (p-p)	–	–	0.005 (0.01%)	0.01	$2 \bullet T_{dck}$
Phase jitter (p-p)	Integer MF, FPL mode, Vcc=1.8V	–	1.0 (10%)	1.5	ns
Power supply voltage	–	1.7	–	2.5	V
Power dissipation	FOL mode, integer MF, f_{dck} = 200 MHz, Vcc = 1.8V	–	–	4	mW

Table 12. EIM Bus Timing Parameter Table (Continued)

Ref No.	Parameter	1.8 ± 0.1 V			3.0 ± 0.3 V			Unit
		Min	Typical	Max	Min	Typical	Max	
4a	Clock[1] rise to Output Enable Valid	2.32	2.62	6.85	2.3	2.6	6.8	ns
4b	Clock[1] rise to Output Enable Invalid	2.11	2.52	6.55	2.1	2.5	6.5	ns
4c	Clock[1] fall to Output Enable Valid	2.38	2.69	7.04	2.3	2.6	6.8	ns
4d	Clock[1] fall to Output Enable Invalid	2.17	2.59	6.73	2.1	2.5	6.5	ns
5a	Clock[1] rise to Enable Bytes Valid	1.91	2.52	5.54	1.9	2.5	5.5	ns
5b	Clock[1] rise to Enable Bytes Invalid	1.81	2.42	5.24	1.8	2.4	5.2	ns
5c	Clock[1] fall to Enable Bytes Valid	1.97	2.59	5.69	1.9	2.5	5.5	ns
5d	Clock[1] fall to Enable Bytes Invalid	1.76	2.48	5.38	1.7	2.4	5.2	ns
6a	Clock[1] fall to Load Burst Address Valid	2.07	2.79	6.73	2.0	2.7	6.5	ns
6b	Clock[1] fall to Load Burst Address Invalid	1.97	2.79	6.83	1.9	2.7	6.6	ns
6c	Clock[1] rise to Load Burst Address Invalid	1.91	2.62	6.45	1.9	2.6	6.4	ns
7a	Clock[1] rise to Burst Clock rise	1.61	2.62	5.64	1.6	2.6	5.6	ns
7b	Clock[1]rise to Burst Clock fall	1.61	2.62	5.84	1.6	2.6	5.8	ns
7c	Clock[1] fall to Burst Clock rise	1.55	2.48	5.59	1.5	2.4	5.4	ns
7d	Clock[1] fall to Burst Clock fall	1.55	2.59	5.80	1.5	2.5	5.6	ns
8a	Read Data setup time	5.54	–	–	5.5	–	–	ns
8b	Read Data hold time	0	–	–	0	–	–	ns
9a	Clock[1] rise to Write Data Valid	1.81	2.72	6.85	1.8	2.7	6.8	ns
9b	Clock[1] fall to Write Data Invalid	1.45	2.48	5.69	1.4	2.4	5.5	ns
9c	Clock[1] rise to Write Data Invalid	1.63	–	–	1.62	–	–	ns
10a	$\overline{\text{DTACK}}$ setup time	2.52	–	–	2.5	–	–	ns

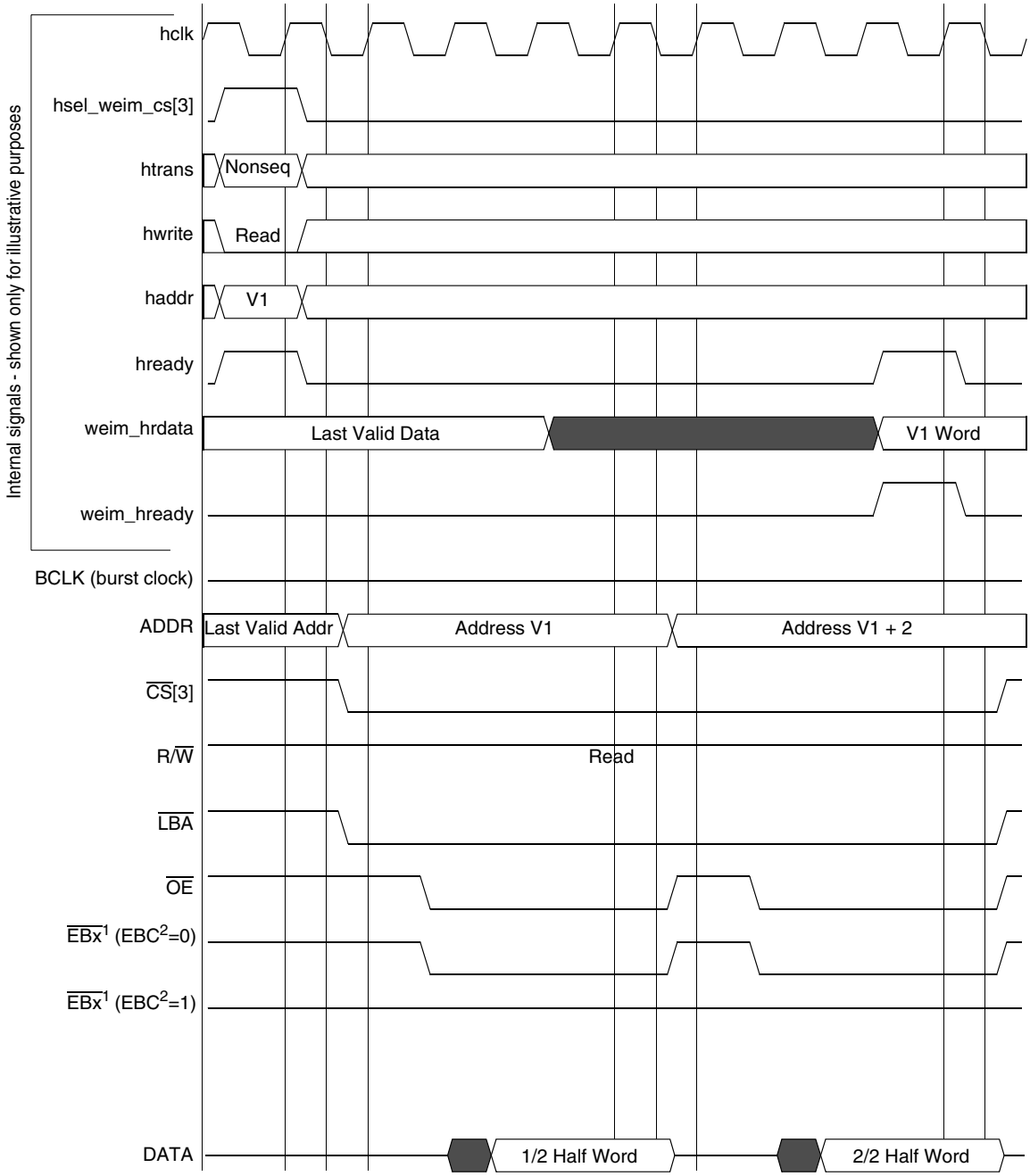
[1] Clock refers to the system clock signal, HCLK, generated from the System DPLL

4.4.1 $\overline{\text{DTACK}}$ Signal Description

The $\overline{\text{DTACK}}$ signal is the external input data acknowledge signal. When using the external $\overline{\text{DTACK}}$ signal as a data acknowledge signal, the bus time-out monitor generates a bus error when a bus cycle is not terminated by the external $\overline{\text{DTACK}}$ signal after 1022 HCLK counts have elapsed. Only the CS5 group supports DTACK signal function when the external DTACK signal is used for data acknowledgement.

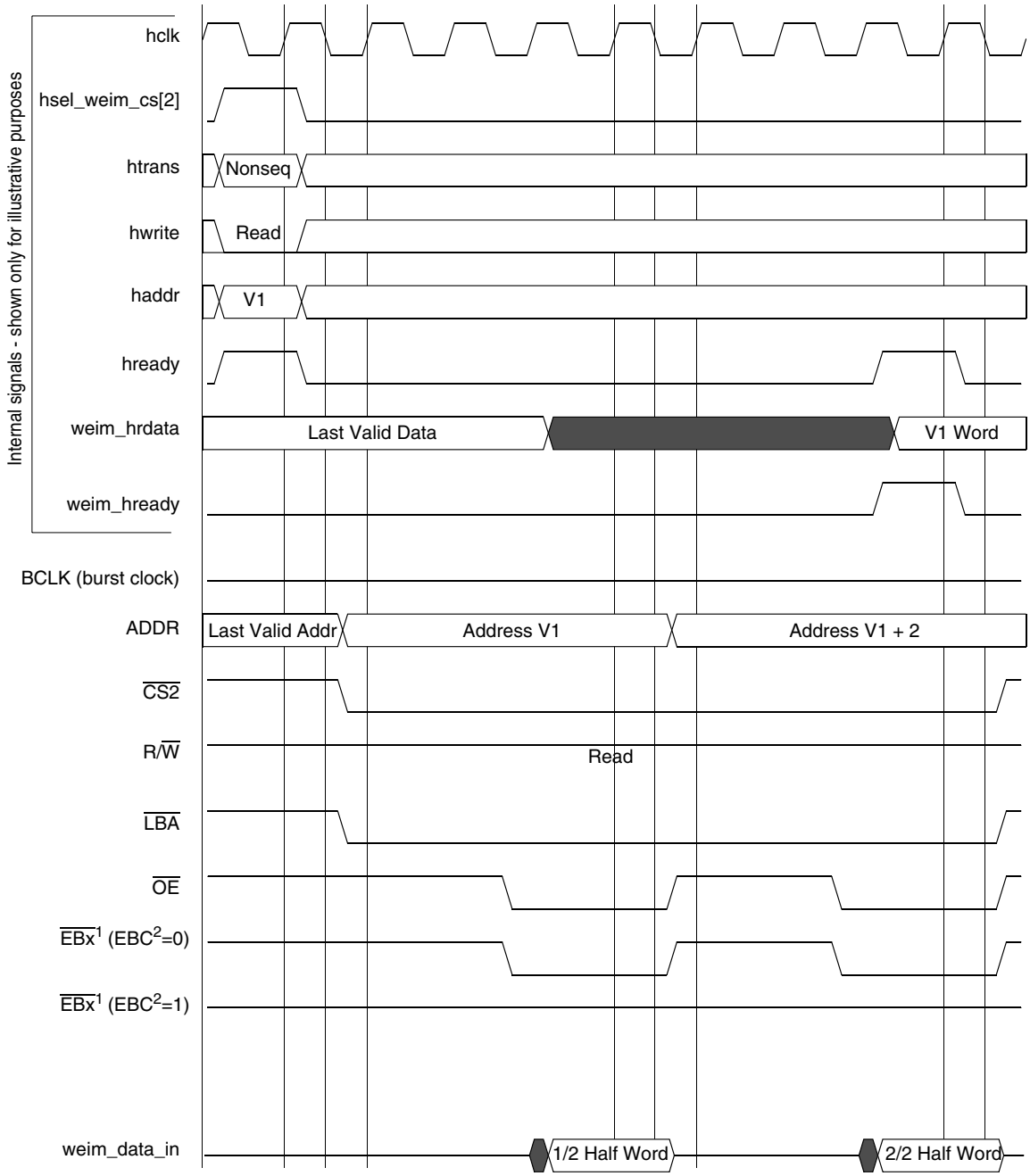
4.4.2 $\overline{\text{DTACK}}$ Signal Timing

Figure 6 through Figure 9 show the access cycle timing used by chip-select 5. The signal values and units of measure for this figure are found in the associated tables.



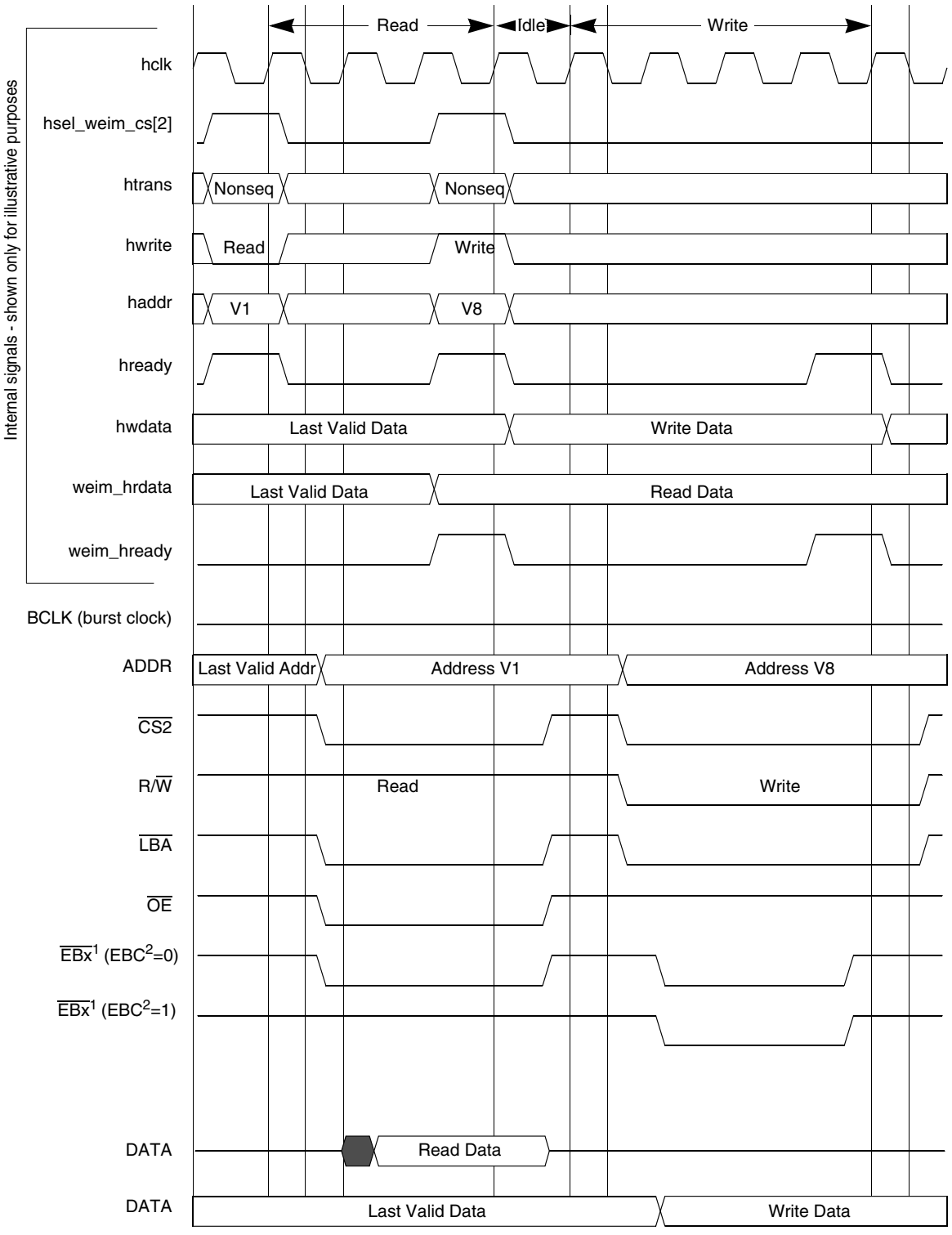
Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 14. WSC = 3, OEA = 2, A.WORD/E.HALF



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 16. WSC = 3, OEA = 4, A.WORD/E.HALF



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 23. WSC = 2, WWS = 1, WEA = 1, WEN = 2, EDC = 1, A.HALF/E.HALF

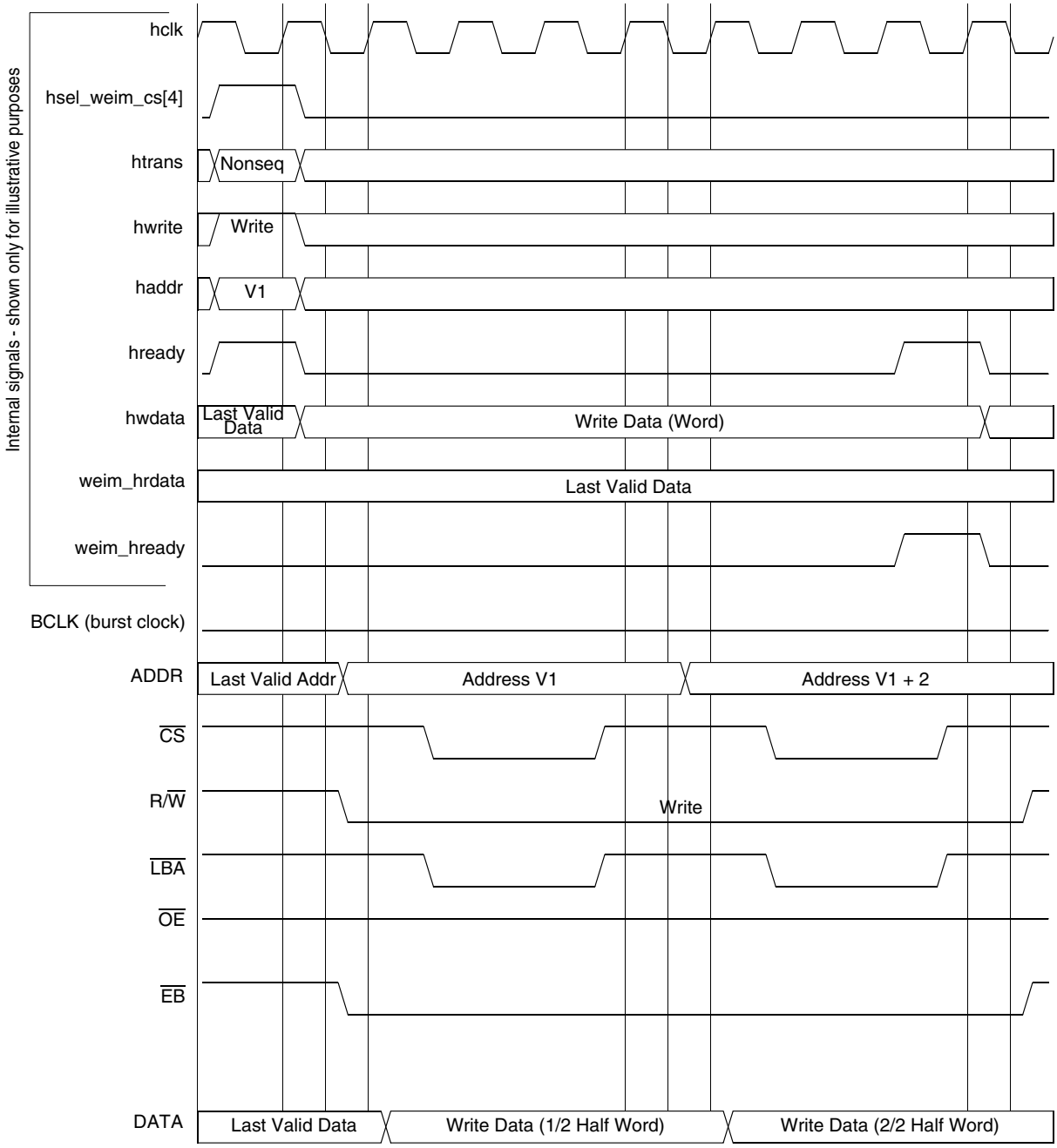
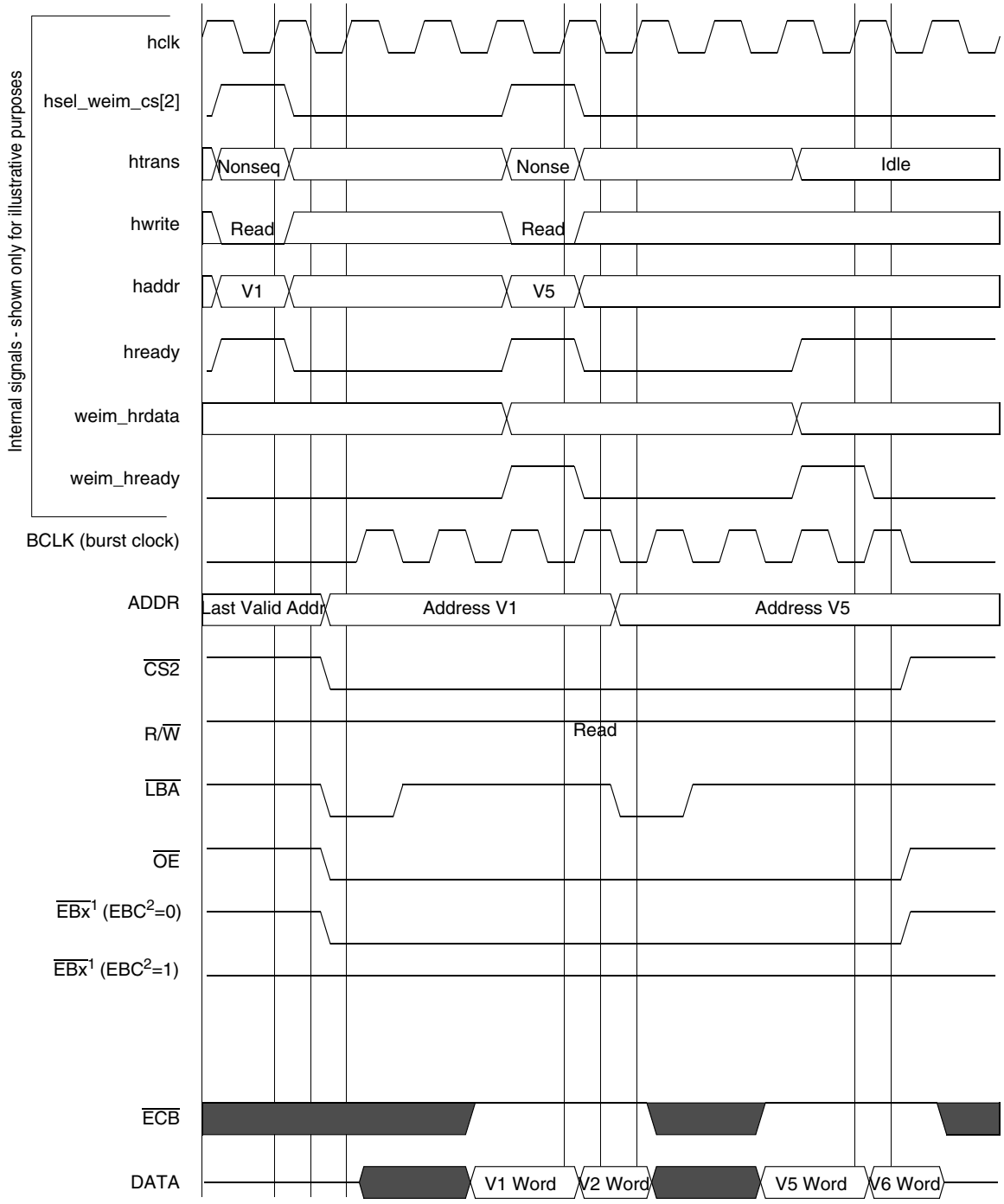
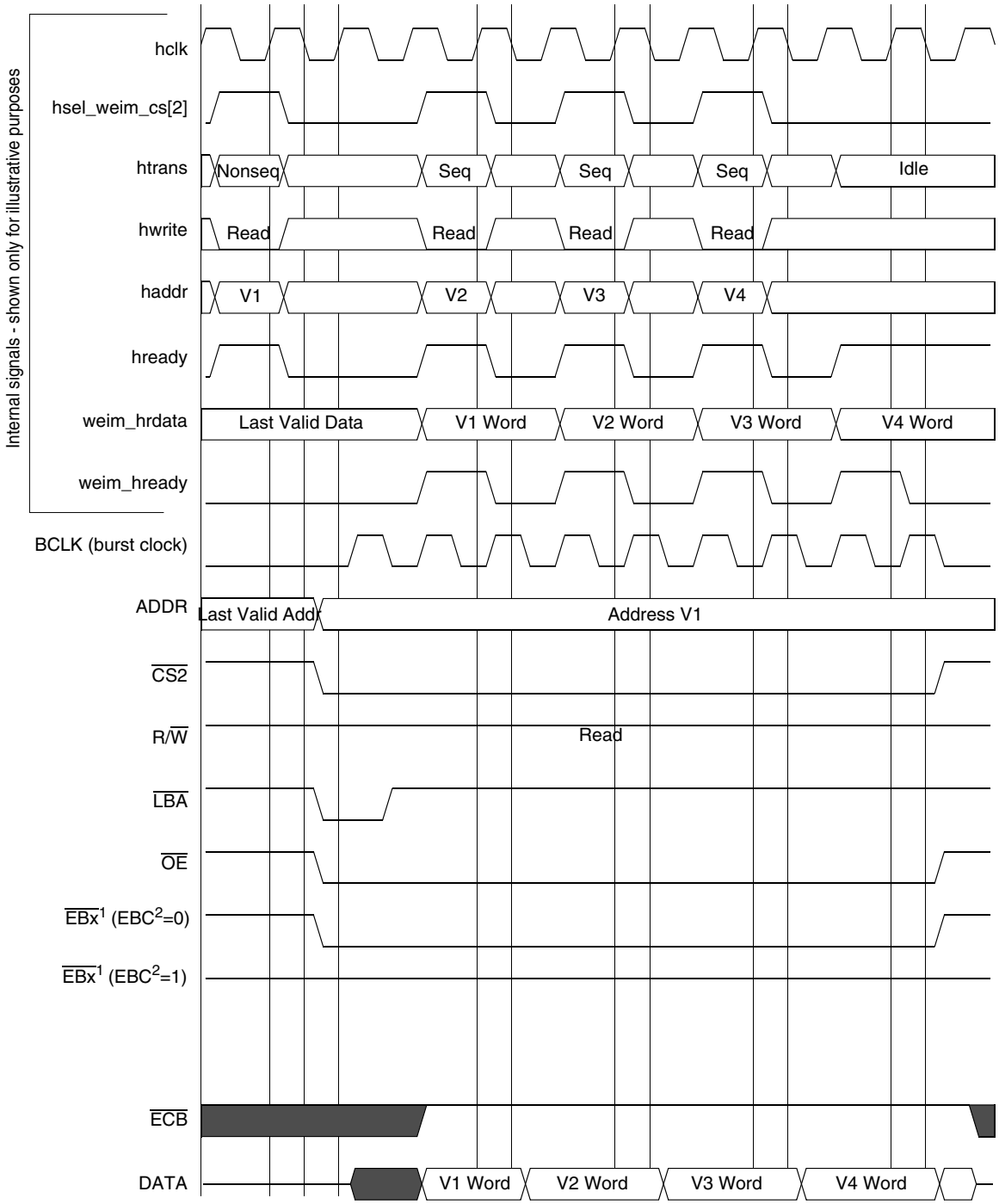


Figure 24. WSC = 2, CSA = 1, WWS = 1, A.WORD/E.HALF



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 28. WSC = 3, SYNC = 1, A.HALF/E.HALF



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 29. WSC = 2, SYNC = 1, DOL = [1/0], A.WORD/E.WORD

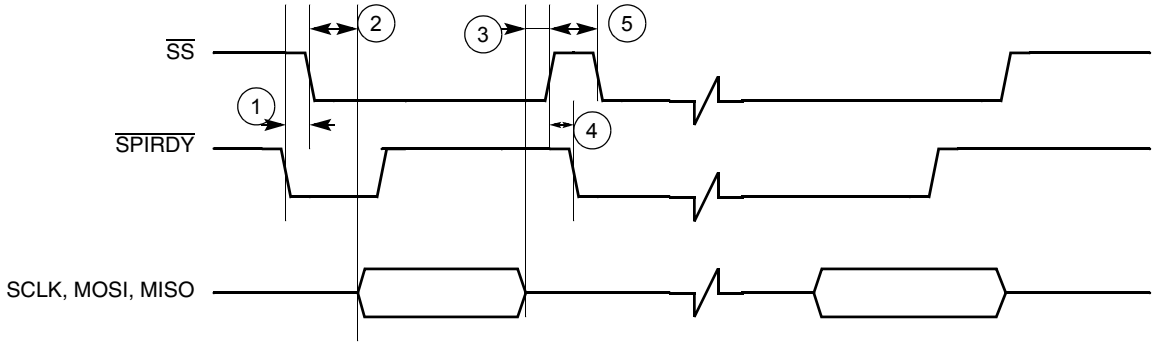


Figure 34. Master SPI Timing Diagram Using SPI_RDY Edge Trigger

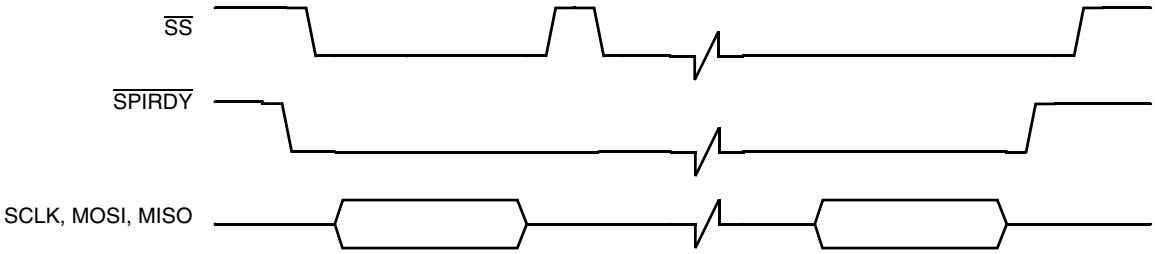


Figure 35. Master SPI Timing Diagram Using SPI_RDY Level Trigger

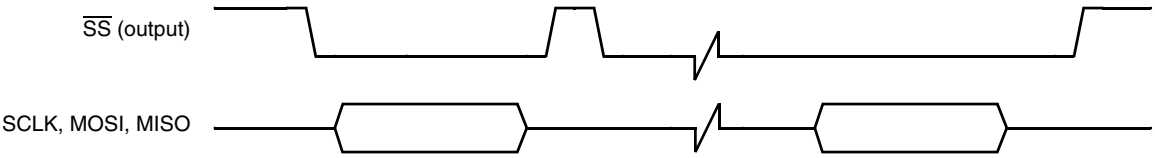


Figure 36. Master SPI Timing Diagram Ignore SPI_RDY Level Trigger

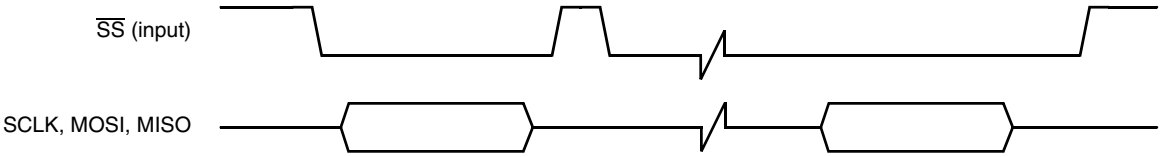


Figure 37. Slave SPI Timing Diagram FIFO Advanced by BIT COUNT

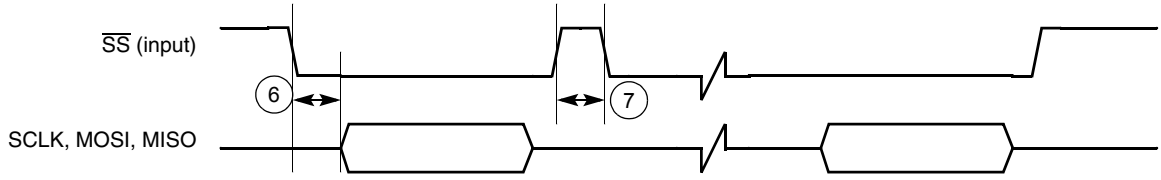


Figure 38. Slave SPI Timing Diagram FIFO Advanced by SS Rising Edge

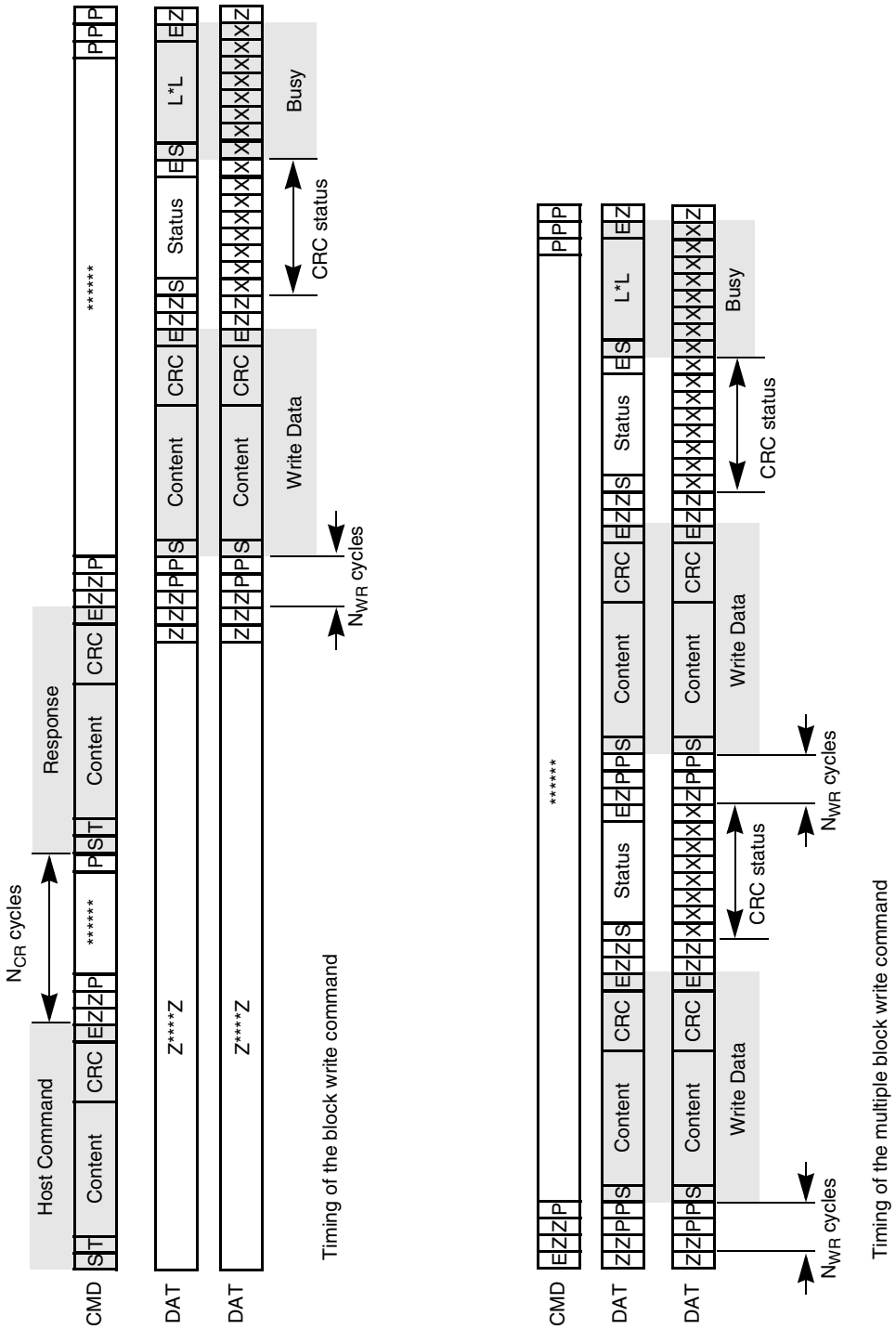


Figure 46. Timing Diagrams at Data Write

The stop transmission command may occur when the card is in different states. Figure 47 shows the different scenarios on the bus.

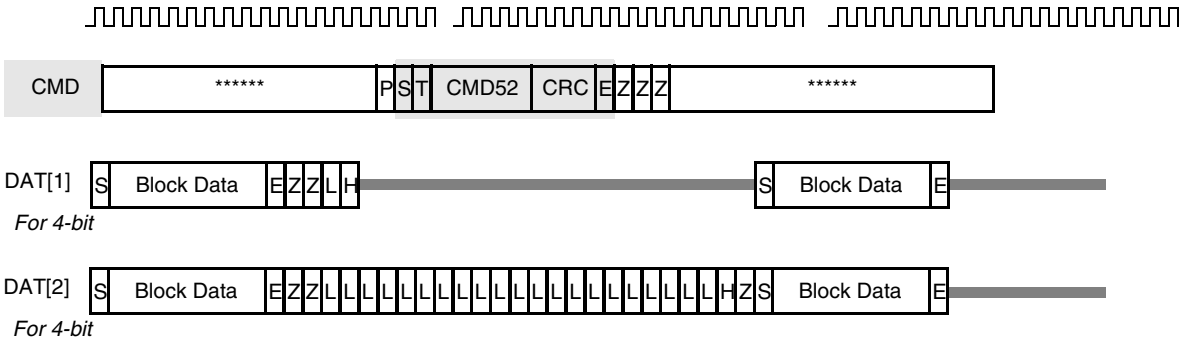


Figure 49. SDIO ReadWait Timing Diagram

4.8 Memory Stick Host Controller

The Memory Stick protocol requires three interface signal line connections for data transfers: MS_BS, MS_SDIO, and MS_SCLKO. Communication is always initiated by the MSHC and operates the bus in either four-state or two-state access mode.

The MS_BS signal classifies data on the SDIO into one of four states (BS0, BS1, BS2, or BS3) according to its attribute and transfer direction. BS0 is the INT transfer state, and during this state no packet transmissions occur. During the BS1, BS2, and BS3 states, packet communications are executed. The BS1, BS2, and BS3 states are regarded as one packet length and one communication transfer is always completed within one packet length (in four-state access mode).

The Memory Stick usually operates in four state access mode and in BS1, BS2, and BS3 bus states. When an error occurs during packet communication, the mode is shifted to two-state access mode, and the BS0 and BS1 bus states are automatically repeated to avoid a bus collision on the SDIO.

Table 25. MSHC Signal Timing Parameter Table (Continued)

Ref No.	Parameter	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
12	MS_SDIO output delay time[1,2]	–	3	ns
13	MS_SDIO input setup time for MS_SCLKO rising edge (RED bit = 0)[3]	18	–	ns
14	MS_SDIO input hold time for MS_SCLKO rising edge (RED bit = 0)[3]	0	–	ns
15	MS_SDIO input setup time for MS_SCLKO falling edge (RED bit = 1)[4]	23	–	ns
16	MS_SDIO input hold time for MS_SCLKO falling edge (RED bit = 1)[4]	0	–	ns

1 Loading capacitor condition is less than or equal to 30pF.

2 An external resistor (100 ~ 200 ohm) should be inserted in series to provide current control on the MS_SDIO pin, because of a possibility of signal conflict between the MS_SDIO pin and Memory Stick SDIO pin when the pin direction changes.

3 If the MSC2[RED] bit = 0, MSHC samples MS_SDIO input data at MS_SCLKO rising edge.

4 If the MSC2[RED] bit = 1, MSHC samples MS_SDIO input data at MS_SCLKO falling edge.

4.9 Pulse-Width Modulator

The PWM can be programmed to select one of two clock signals as its source frequency. The selected clock signal is passed through a divider and a prescaler before being input to the counter. The output is available at the pulse-width modulator output (PWMO) external pin. Its timing diagram is shown in Figure 51 and the parameters are listed in Table 26.

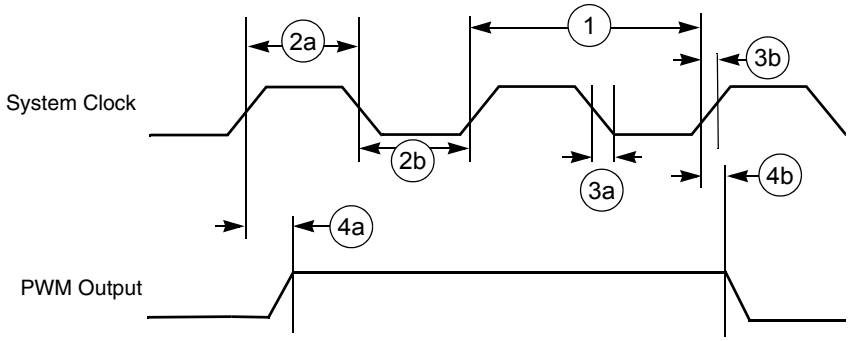


Figure 51. PWM Output Timing Diagram

Table 26. PWM Output Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
1	System CLK frequency[1]	0	87	0	100	MHz
2a	Clock high time[1]	3.3	–	5/10	–	ns
2b	Clock low time[1]	7.5	–	5/10	–	ns
3a	Clock fall time[1]	–	5	–	5/10	ns

Table 27. SDRAM Read Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
1	SDRAM clock high-level width	2.67	–	4	–	ns
2	SDRAM clock low-level width	6	–	4	–	ns
3	SDRAM clock cycle time	11.4	–	10	–	ns
3S	CS, RAS, CAS, WE, DQM setup time	3.42	–	3	–	ns
3H	CS, RAS, CAS, WE, DQM hold time	2.28	–	2	–	ns
4S	Address setup time	3.42	–	3	–	ns
4H	Address hold time	2.28	–	2	–	ns
5	SDRAM access time (CL = 3)	–	6.84	–	6	ns
5	SDRAM access time (CL = 2)	–	6.84	–	6	ns
5	SDRAM access time (CL = 1)	–	22	–	22	ns
6	Data out hold time	2.85	–	2.5	–	ns
7	Data out high-impedance time (CL = 3)	–	6.84	–	6	ns
7	Data out high-impedance time (CL = 2)	–	6.84	–	6	ns
7	Data out high-impedance time (CL = 1)	–	22	–	22	ns
8	Active to read/write command period (RC = 1)	t_{RCD}[1]	–	t_{RCD1}	–	ns

[1] t_{RCD} = SDRAM clock cycle time. This settings can be found in the *MC9328MXL reference manual*.

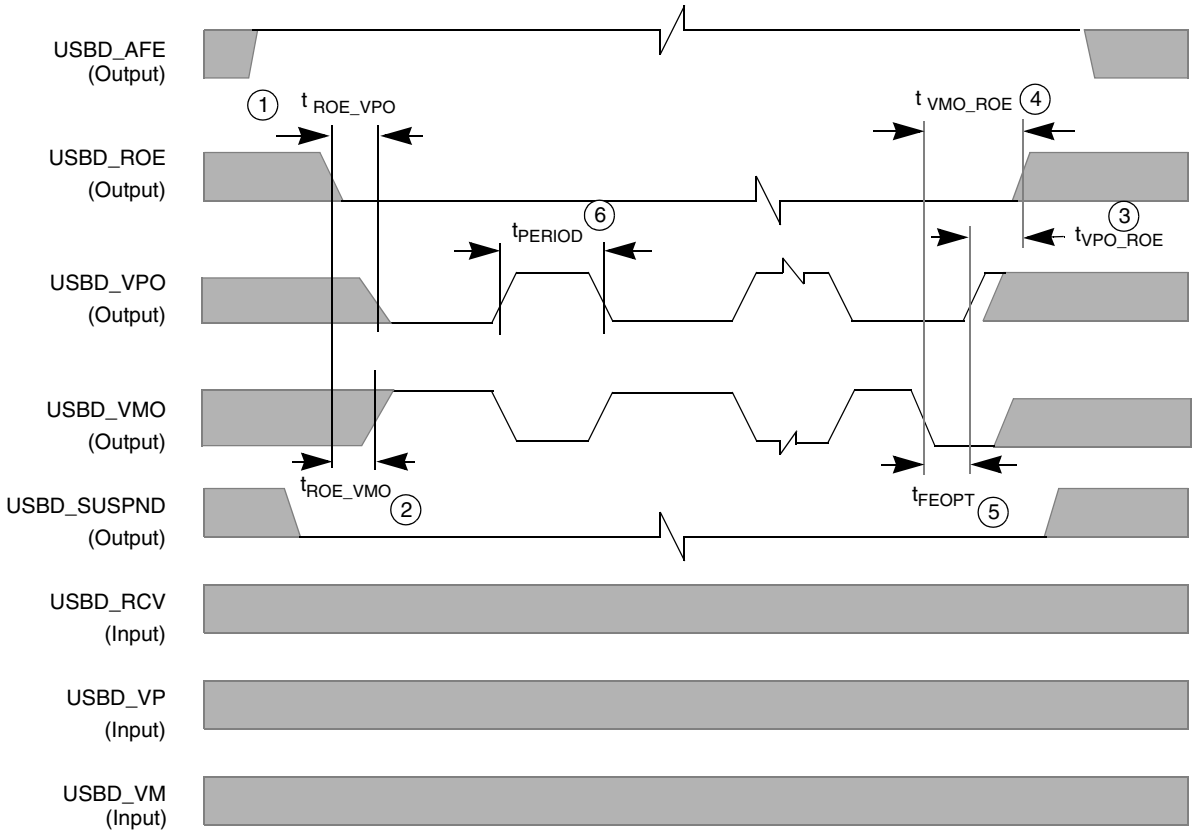


Figure 56. USB Device Timing Diagram for Data Transfer to USB Transceiver (TX)

Table 30. USB Device Timing Parameters for Data Transfer to USB Transceiver (TX)

Ref No.	Parameter	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	t_{ROE_VPO}; USBD_ROE active to USBD_VPO low	83.14	83.47	ns
2	t_{ROE_VMO}; USBD_ROE active to USBD_VMO high	81.55	81.98	ns
3	t_{VPO_ROE}; USBD_VPO high to USBD_ROE deactivated	83.54	83.80	ns
4	t_{VMO_ROE}; USBD_VMO low to USBD_ROE deactivated (includes SE0)	248.90	249.13	ns
5	t_{FEOPT}; SE0 interval of EOP	160.00	175.00	ns
6	t_{PERIOD}; Data transfer rate	11.97	12.03	Mb/s

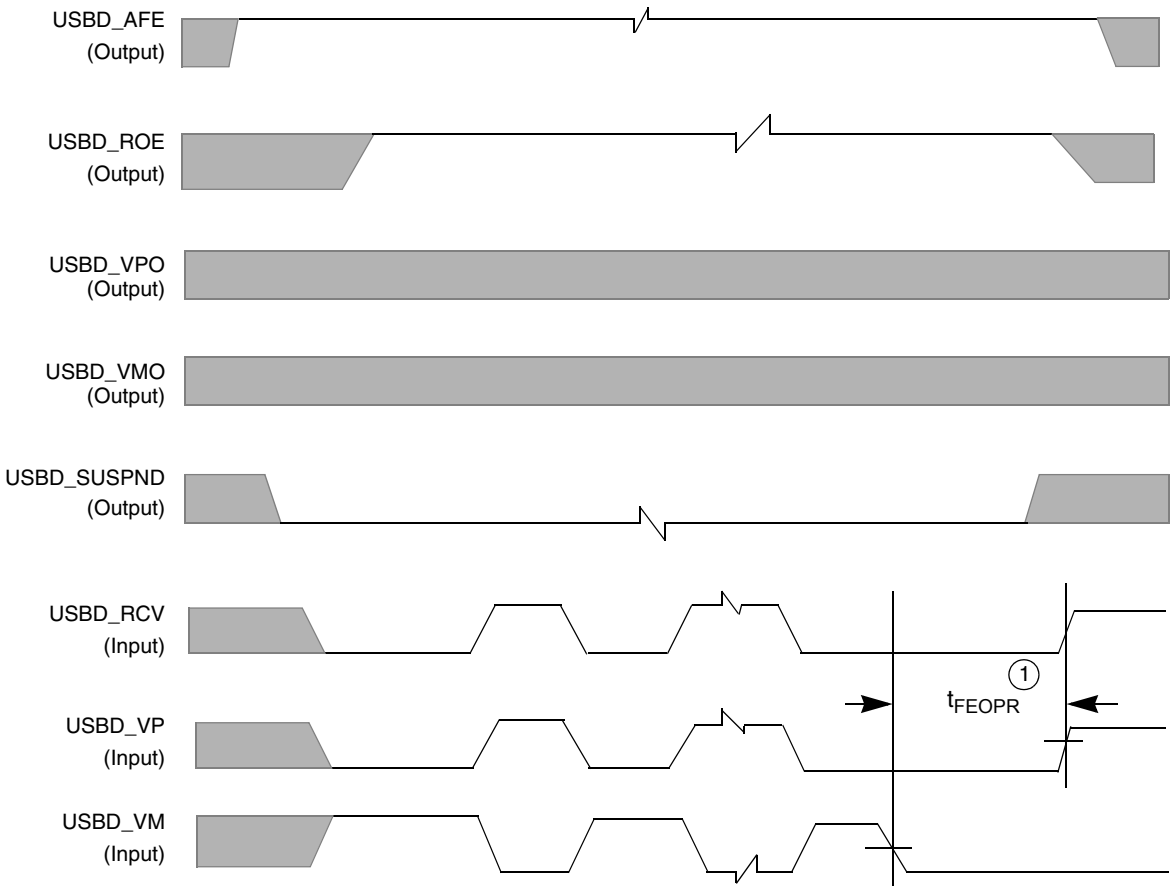


Figure 57. USB Device Timing Diagram for Data Transfer from USB Transceiver (RX)

Table 31. USB Device Timing Parameter Table for Data Transfer from USB Transceiver (RX)

Ref No.	Parameter	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	t_{FEOPR}; Receiver SE0 interval of EOP	82	–	ns

4.12 I²C Module

The I²C communication protocol consists of seven elements: START, Data Source/Recipient, Data Direction, Slave Acknowledge, Data, Data Acknowledge, and STOP.

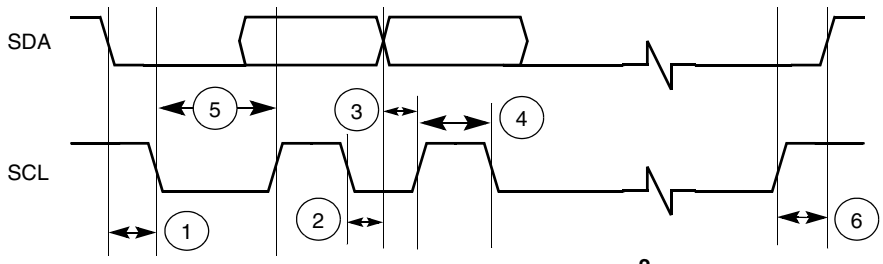


Figure 58. Definition of Bus Timing for I²C

Table 33. SSI (Port C Primary Function) Timing Parameter Table (Continued)

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
18	STCK high to STFS (bl) high[3]	–	92.8	0	81.4	ns
19	SRCK high to SRFS (bl) high[3]	–	92.8	0	81.4	ns
20	STCK high to STFS (bl) low[3]	–	92.8	0	81.4	ns
21	SRCK high to SRFS (bl) low[3]	–	92.8	0	81.4	ns
22	STCK high to STFS (wl) high[3]	–	92.8	0	81.4	ns
23	SRCK high to SRFS (wl) high[3]	–	92.8	0	81.4	ns
24	STCK high to STFS (wl) low[3]	–	92.8	0	81.4	ns
25	SRCK high to SRFS (wl) low[3]	–	92.8	0	81.4	ns
26	STCK high to STXD valid from high impedance	18.01	28.16	15.8	24.7	ns
27a	STCK high to STXD high	8.98	18.13	7.0	15.9	ns
27b	STCK high to STXD low	9.12	18.24	8.0	16.0	ns
28	STCK high to STXD high impedance	18.47	28.5	16.2	25.0	ns
29	SRXD setup time before SRCK low	1.14	–	1.0	–	ns
30	SRXD hole time after SRCK low	0	–	0	–	ns
Synchronous Internal Clock Operation (Port C Primary Function[2])						
31	SRXD setup before STCK falling	15.4	–	13.5	–	ns
32	SRXD hold after STCK falling	0	–	0	–	ns
Synchronous External Clock Operation (Port C Primary Function[2])						
33	SRXD setup before STCK falling	1.14	–	1.0	–	ns
34	SRXD hold after STCK falling	0	–	0	–	ns

1 All the timings for the SSI are given for a non-inverted serial clock polarity (TSCKP/RSCKP = 0) and a non-inverted frame sync (TFSI/RFSI = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timing remains valid by inverting the clock signal STCK/SRCK and/or the frame sync STFS/SRFS shown in the tables and in the figures.

2 There are 2 sets of I/O signals for the SSI module. They are from Port C primary function (pad 257 to pad 261) and Port B alternate function (pad 283 to pad 288). When SSI signals are configured as outputs, they can be viewed both at Port C primary function and Port B alternate function. When SSI signals are configured as input, the SSI module selects the input based on status of the FMCR register bits in the Clock controller module (CRM). By default, the input are selected from Port C primary function.

3 bl = bit length; wl = word length.

NOTES